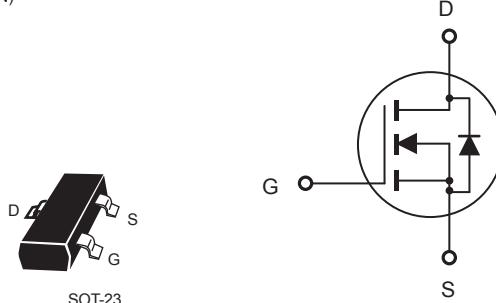


- 30V, 4.8A,  $R_{DS(ON)} = 34m\Omega$  @ $V_{GS} = 10V$ .
- $R_{DS(ON)} = 40m\Omega$  @ $V_{GS} = 4.5V$ .
- $R_{DS(ON)} = 60m\Omega$  @ $V_{GS} = 2.5V$ .
- High dense cell design for extremely low  $R_{DS(ON)}$ .
- Rugged and reliable.
- Lead free product is acquired.
- SOT-23 package.



## ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	4.8	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	20	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating and Store Temperature Range	$T_J, T_{Stg}$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	100	$^\circ C/W$

# CES2310

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 12\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -12\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	0.6		1.4	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 4.8\text{A}$		28	34	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 4\text{A}$		32	40	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 2\text{A}$		45	60	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 10\text{V}, I_D = 4.8\text{A}$		12		S
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		610		pF
Output Capacitance	$C_{\text{oss}}$			125		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			80		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 4.8\text{A}, \square$ $V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 3\Omega$		10	20	ns
Turn-On Rise Time	$t_r$			3	6	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			35	70	ns
Turn-Off Fall Time	$t_f$			4	8	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 4.8\text{A},$ $V_{\text{GS}} = 4.5\text{V}$		9.0	12	nC
Gate-Source Charge	$Q_{\text{gs}}$			2.3		nC
Gate-Drain Charge	$Q_{\text{gd}}$			2.2		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				4.8	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1\text{A}$			1	V

**Notes :**

a.Repetitive Rating : Pulse width limited by maximum junction temperature.

b.Surface Mounted on FR4 Board,  $t < 5 \text{ sec}$ .

c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

d.Guaranteed by design, not subject to production testing.